

HEAT-STABLE HOT-MELT ADHESIVE COMPOSITION

Publication number: JP2000204334
Publication date: 2000-07-25
Inventor: SUZUKI HIROAKI
Applicant: HITACHI KASEI POLYMER CO. LTD.
Classification:
international: C09J 11/06, C09J 109/06, C09J 125/08, C09J 11/02,
C09J 109/00, C09J 125/00, IPC 1-7: C09J 109/06,
C09J 11/06, C09J 125/08
European:
Application number: JP19990038992 19990108
Priority number(s): JP19990038992 19990108

Report a data error here

Abstract of JP2000204334

PROBLEM TO BE SOLVED: To obtain the subject adhesive composition by incorporating a metal deactivator in a rubber-based hot-melt adhesive comprising a styrene-based thermoplastic rubber, a tackifying resin and a plasticizer so as to suppress its gelation under continuous heating, decline in its cohesive and adhesive power and discoloration and offensive odor emission and thus improve its thermal stability. **SOLUTION:** This hot-melt adhesive composition is obtained by incorporating 100 pts.wt. of a composition comprising 10-50 pts.wt. of a styrene-based thermoplastic rubber, 20-65 pts.wt. of a tackifying resin and 5-30 pts.wt. of a plasticizer with ≥ 0.001 pt.wt. of a hydrazine-based metal deactivator. The deactivator has such effect as to deactivate the deteriorative action of the residual metal catalyst on the styrene-based thermoplastic rubber, tackifying resin, plasticizer, etc., in this adhesive composition, leading to significantly improving this hot-melt adhesive composition in viscosity and hue change due to heat, and skinning, etc.

Data supplied from the esp@cenet database - Worldwide